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July 2014

FDFMA2P029Z

Integrated P-Channel PowerTrench® MOSFET and Schottky Diode

-20V, -3.1A, 95mΩ

Features

MOSFET

- Max $r_{DS(on)}$ = 95m Ω at V_{GS} = -4.5V, I_D = -3.1A
- Max $r_{DS(on)} = 141 \text{m}\Omega$ at $V_{GS} = -2.5 \text{V}$, $I_D = -2.5 \text{A}$
- HBM ESD protection level > 2.5kV (Note 3)

Schottky

- V_F < 0.37V @ 500mA
- Low profile 0.8 mm maximum in the new package MicroFET 2x2 mm
- RoHS Compliant



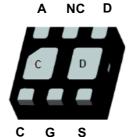
General Description

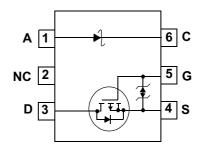
This device is designed specifically as a single package solution for the battery charge switch in cellular handset and other ultraportable applications. It features a MOSFET with very low onstate resistance and an independently connected low forward voltage schottky diode allows for minimum conduction losses.

The MicroFET 2X2 package offers exceptional thermal performance for its physical size and is well suited to linear mode applications.

Pin 1







MicroFET 2X2

MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain to Source Voltage		-20	V
V_{GS}	Gate to Source Voltage		±12	V
1	Drain Current -Continuous (No	te 1a)	-3.1	^
ID	-Pulsed		-6	A
D	Power Dissipation (No	te 1a)	1.4	W
P_{D}	(No	te 1b)	0.7	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C
V_{RRM}	Schottky Repetitive Peak Reverse Voltage		20	V
Io	Schottky Average Forward Current		2	Α

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	86	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	173	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1c)	86	C/VV
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1d)	140	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size Tape		Quantity	
.P29	FDFMA2P029Z	MicroFET 2X2	7"	8mm	3000 units	

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-12		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16V, \ V_{GS} = 0V$			-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 12V$, $V_{DS} = 0V$			±10	μΑ

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.6	-1.0	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu A$, referenced to 25°C		4		mV/°C
		$V_{GS} = -4.5V, I_D = -3.1A$		60	95	
r _{DS(on)}	Static Drain to Source On-Resistance	$V_{GS} = -2.5V$, $I_D = -2.5A$		88	141	mΩ
		$V_{GS} = -4.5V$, $I_D = -3.1A$, $T_J = 125$ °C		87	140	
9 _{FS}	Forward Transconductance	$V_{DS} = -10V, I_D = -3.1A$		-11		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 10V V - 0V	540	720	pF
C _{oss}	Output Capacitance	V _{DS} = -10V, V _{GS} = 0V, f = 1MHz	120	160	pF
C _{rss}	Reverse Transfer Capacitance	1171112	100	150	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	101/1	13	24	ns
t _r	Rise Time	$V_{DD} = -10V, I_{D} = -1A$ $V_{GS} = -4.5V, R_{GEN} = 6\Omega$	11	20	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -4.5V, N _{GEN} = 052	37	59	ns
t _f	Fall Time		36	58	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{DD} = -10V, I_D = -3.1A$	7	10	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = -4.5V	1.1		nC
Q _{gd}	Gate to Drain "Miller" Charge		2.4		nC

Drain-Source Diode Characteristics

Is	Maximum Continuous Drain-Source Diode Forward Current				-1.1	Α
V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = -1.1A$ (Note 2)		-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	I _E = -3.1A, di/dt = 100A/μs		25		ns
Q _{rr}	Reverse Recovery Charge	ης – –3.1Α, αναί – 100Α/μs		9		nC

Schottky Diode Characteristics

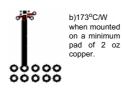
V_R	Reverse Voltage	I _R = 1mA	T _J = 25°C	20			V
	Poverse Leekege	V = 20V	T _J = 25°C		30	300	μΑ
^I R	Reverse Leakage	V _R = 20V	$T_{J} = 125^{\circ}C$		10	45	mA
	L = 500A	I = 500mA	T _J = 25°C		0.32	0.37	
V	Fanyard Voltage	I _F = 500mA	$T_{J} = 125^{\circ}C$		0.21 0.26	0.26	V
V _F	Forward Voltage	I _E = 1A	T _J = 25°C		0.37	0.435	V
		IF - IA	$T_{J} = 125^{\circ}C$		0.28	0.33	

Notes:

- 1: R_{BJA} is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{BJC} is guaranteed by design while R_{BJA} is determined by the user's board design.
 - (a) MOSFET $R_{\theta JA}$ = 86°C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB
 - (b) MOSFET $R_{\theta JA}$ = 173°C/W when mounted on a minimum pad of 2 oz copper
 - (c) Schottky R $_{\theta JA}$ = 86°C/W when mounted on a 1in 2 pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB.
 - (d) Schottky $R_{\theta JA}$ = 140°C/W when mounted on a minimum pad of 2 oz copper.



a)86°C/W when mounted on a 1in² pad of 2 oz copper.



....

c)86°C/W when mounted on a 1in² pad of 2 oz copper.



d)140°C/W when mounted on a minimum pad of 2 oz copper.

- 2: Pulse Test: Pulse Width < 300us, Duty Cycle < 2.0%
- 3. The diode connected between the gate and source serves only protection against ESD. No gate overvoltage rating is implied.



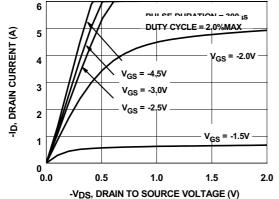


Figure 1. On Region Characteristics

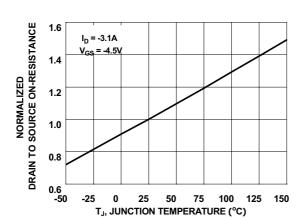


Figure 3. Normalized On-Resistance vs Junction Temperature

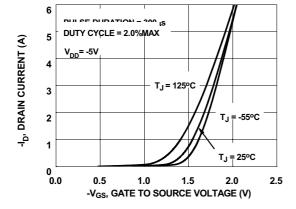


Figure 5. Transfer Characteristics

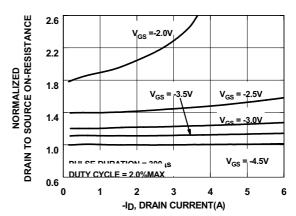


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

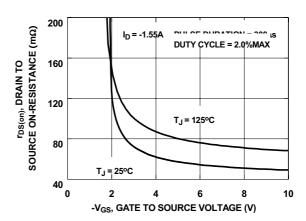


Figure 4. On-Resistance vs Gate to Source Voltage

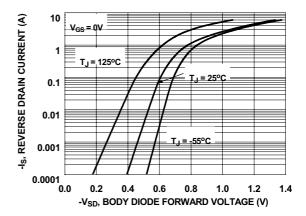


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

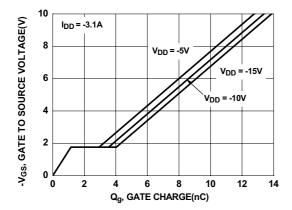


Figure 7. Gate Charge Characteristics

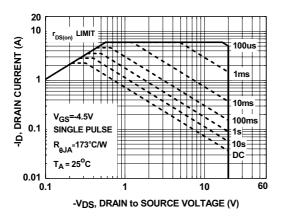


Figure 9. Forward Bias Safe Operating Area

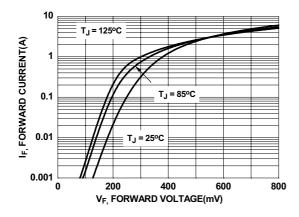


Figure 11. Schottky Diode Forward Voltage

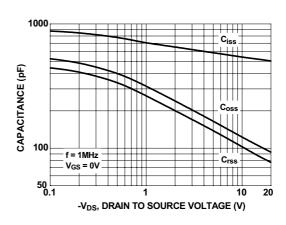


Figure 8. Capacitance Characteristics

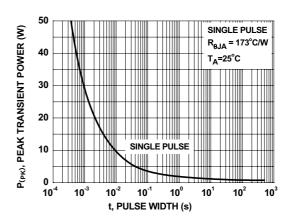


Figure 10. Single Pulse Maximum Power Dissipation

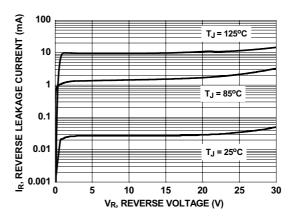


Figure 12. Schottky Diode Reverse Current

Typical Characteristics T_J = 25°C unless otherwise noted

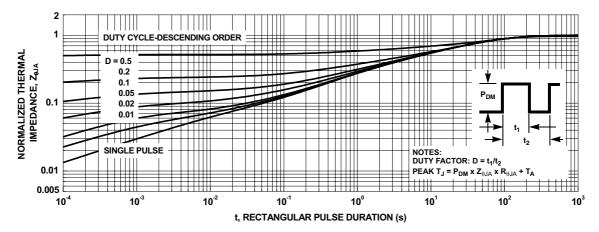
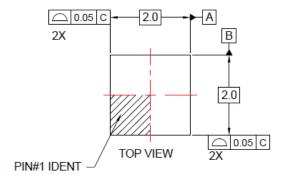
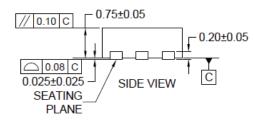
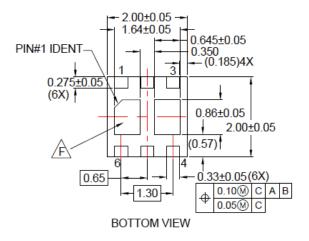


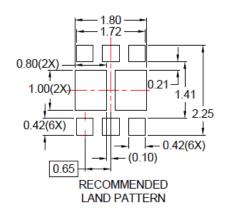
Figure 13. Transient Thermal Response Curve

Dimensional Outline and Pad Layout









NOTES:

- A. CONFORM TO JADEC REGISTRATIONS MO-229, VARIATION VCCC, EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP16Erev4
- F. NON-JEDEC DUAL DAP



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